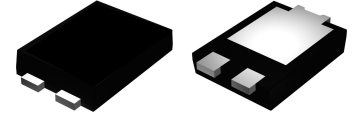
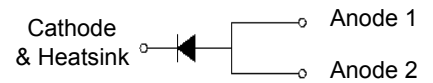


Features

- Low profile - typical height 1.1 mm
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- High temperature soldering guaranteed: 260°C/10 seconds
- Halogen-free according to IEC 61249-2-21 definition



Package:
eSGC (TO-277)



Schematic Diagram

Applications

For low voltage high frequency inverters, DC/DC converters and polarity protection applications.

Maximum Ratings (T_A = 25°C unless otherwise noted)

Parameter	Symbol	GGC2550	GGC2560	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	60	V
Maximum RMS Voltage	V _{RMS}	35	42	V
Maximum DC Blocking Voltage	V _{DC}	50	60	V
Maximum Average Forward Rectified Current	I _{F(AV)}	25.0		A
Peak Forward Surge Current (8.3 ms single half sine-wave superimposed on rated load)	I _{FSM}	350		A
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150		°C

Electrical Characteristics (T_A = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Typ	Max	Unit	
Instantaneous Forward Voltage	I _F =1A	T _A =25°C	V _F	0.29	-	V
	I _F =3A			0.33	-	
	I _F =5A			0.35	0.40	
	I _F =10A			0.39	-	
	I _F =25A			0.48	0.60	
	I _F =1A	T _A =125°C	0.15	-		
	I _F =3A		0.20	0.25		
	I _F =5A		0.24	0.30		
	I _F =10A		0.30	-		
	I _F =25A		0.45	0.50		
Reverse Current	Rated V _R	I _R	T _A =25°C	0.085	0.5	mA
			T _A =100°C	18	100	
Power Dissipation	FR-4, copper pad area 30x30mm, DC source	P _d	6.0		W	
Typical Junction Capacitance	4.0 V, 1 MHz	C _J	2.0		nF	
Typical Thermal Resistance ¹⁾	Junction to Ambient	R _{θJA}	30		°C/W	
	Junction to Mount	R _{θJM}	1			

Note1) Thermal resistance of junction to ambient or mount, mounted on Al P.C.B with recommended copper pad area

Ratings and Characteristics Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

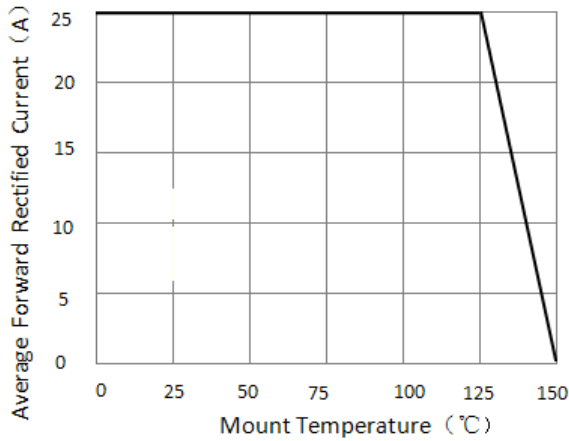


Figure 1. Forward Current Derating Curve

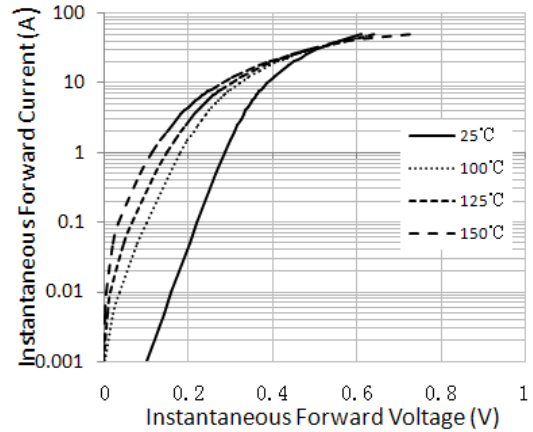


Figure 2. Typical Instantaneous Forward Characteristics

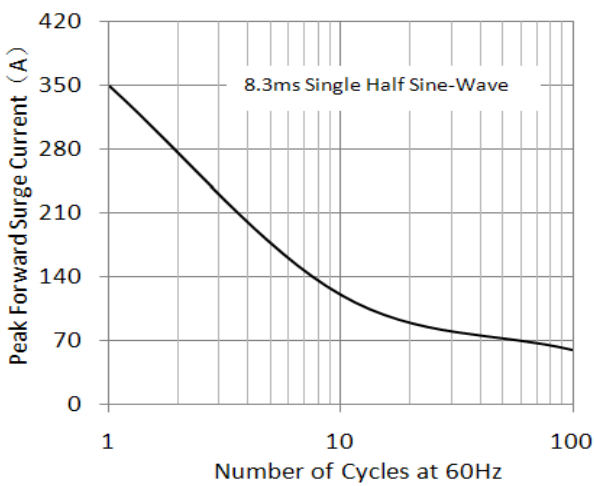


Figure 3. Maximum Non-Repetitive Peak Forward Surge Current

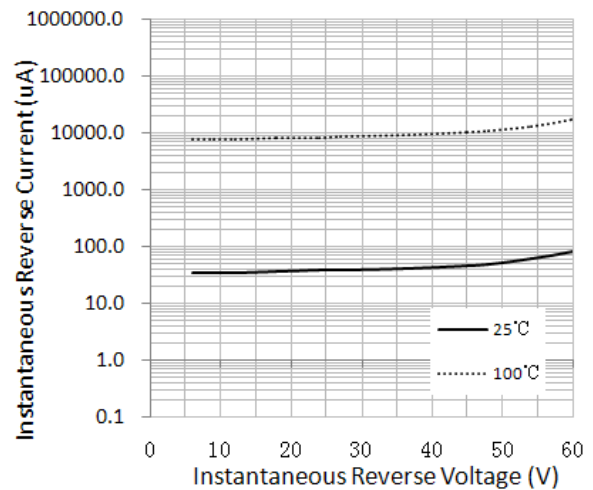


Figure 4. Typical Reverse Characteristics

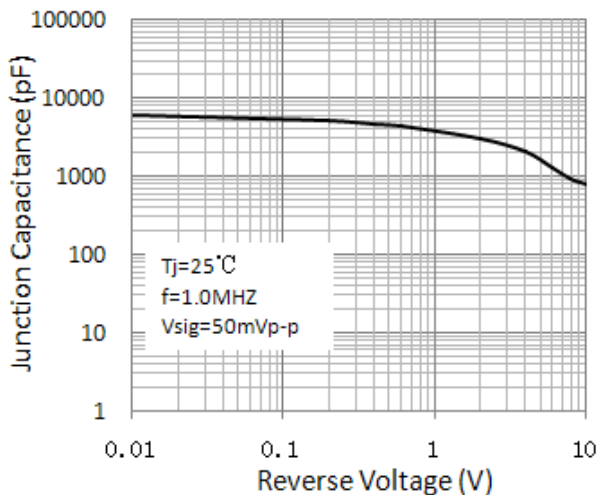
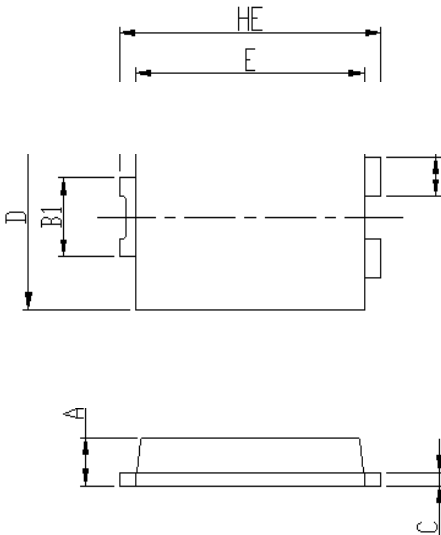


Figure 5. Typical Junction Capacitance

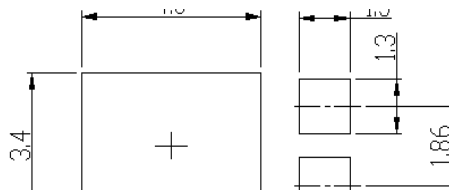
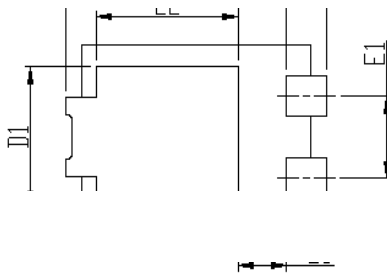
Package Outline Dimensions

eSGC (TO-277)



DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
HE	6.4	6.6	0.252	0.260
E	5.6	5.8	0.220	0.228
D	4.1	4.3	0.161	0.169
B1	1.7	1.9	0.067	0.075
B2	0.8	1	0.031	0.039
A	1.05	1.2	0.041	0.047
C	0.3	0.4	0.012	0.016
L	0.85	1.1	0.033	0.043
L1	4.2	4.4	0.165	0.173
L2	3.52 Typ.		0.139 Typ.	
L3	1.1	1.4	0.043	0.055
D1	3	3.3	0.118	0.130
E1	1.86 Typ.		0.073 Typ.	

Soldering footprint



Packing Information

Packing quantities

5000 pcs/Reel, 12 mm Tape, 13" Reel

Tape & Reel Specification

